

	Hits	Search Text	DBs
13	7	((substrate or wafer or device or platen) same ((registration or alignment) near12 mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4)) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide)) same (mark near14 (alignment or registration))) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment near12 mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) smae (etch\$4 or RIE)) and (((alignment or registration) near15 mark) same (reverse or inverse)) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
14	81	((substrate or wafer or device or platen) same (alignment near12 mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4)) and (((protective near5 layer) or (insulat\$4 near9 layer) or SiO\$3 or (silicon near6 \$4oxide)) same (mark or alignment)) and etch\$4 and (lithograph\$6 or pattern\$4) and (((open\$4 or reveal\$4 or show\$3) near12 (alignment near12 mark)) same (substrate or wafer or surface) same trench\$4 )	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
15	0	((substrate or wafer or device or platen) same ((registration or alignment) near12 mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark near14 (alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and (((alignment or registration) near12 mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) smae (etch\$4 or RIE)) and (((alignment or registration) near15 mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	<b>Hits</b>	<b>Search Text</b>	<b>DBs</b>
16	0	((substrate or wafer or device or platen) same ((registration or alignment) near12 mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark near14 (alignment or registration))) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and (((alignment or registration) near12 mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) smae (etch\$4 or RIE)) and (((alignment or registration) near15 mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US - PGPUB

	Hits	Search Text	DBs
17	0	430/22.ccls. and ((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark near14 (alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and (((alignment or registration) near12 mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) smae (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US_PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

Hits	Search Text	DBs
18 0	430/22.ccls. and ((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror)	US - PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

Hits	Search Text	DBs
19 0	((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and ((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide)) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
20	0	430/313.cc1s. and ((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark or alignment or registration) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
21	0	"430"/\$.ccls. and ((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (open\$4 or reveal\$4 or show\$3) same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror)	US - PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

Hits	Search Text	DBs
22 0	((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide)) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror) and ((laminat\$3 or bond\$4 or attach\$4) same substrate same first same second)	US-PGPUB

	Hits	Search Text	DBs
23	0	430/311.cc1s. and ((substrate or wafer or device or platen or object) same (registration or alignment or mark) same ((first near12 second) or (front near18 back) or (front\$4 near14 rear\$4))) and (((protective near5 (deposit\$3 or layer or film)) or (insulat\$4 near9 (deposit\$4 or layer or film or form\$3)) or SiO\$3 or (silicon near6 \$4oxide))) same (mark or alignment or registration)) and (RIE or etch\$4) and (lithograph\$6 or pattern\$4) and ((alignment or registration or mark) same (substrate or wafer or surface) same trench\$4 same (etch\$4 or RIE)) and ((alignment or registration or mark) same (reverse or inverse) same mirror)	US - PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB